

Dual Voltage Detector With Adjustable Hysteresis

Check for Samples: [TPS3806I33-Q1](#)

FEATURES

- Qualified for Automotive Applications
- AEC-Q100 Qualified With the Following Results:
 - Device Temperature Grade 1: –40°C to 125°C Ambient Operating Temperature Range
 - Device HBM ESD Classification Level H2
 - Device CDM ESD Classification Level C4B
- Dual Voltage Detector With Adjustable Hysteresis, 3.3-V Adjustable and 2-V Adjustable
- Assured Reset at $V_{DD} = 0.8\text{ V}$
- Supply Current: 3 μA Typical at $V_{DD} = 3.3\text{ V}$
- Independent Open-Drain Reset Outputs
- 6-Pin SOT-23 Package

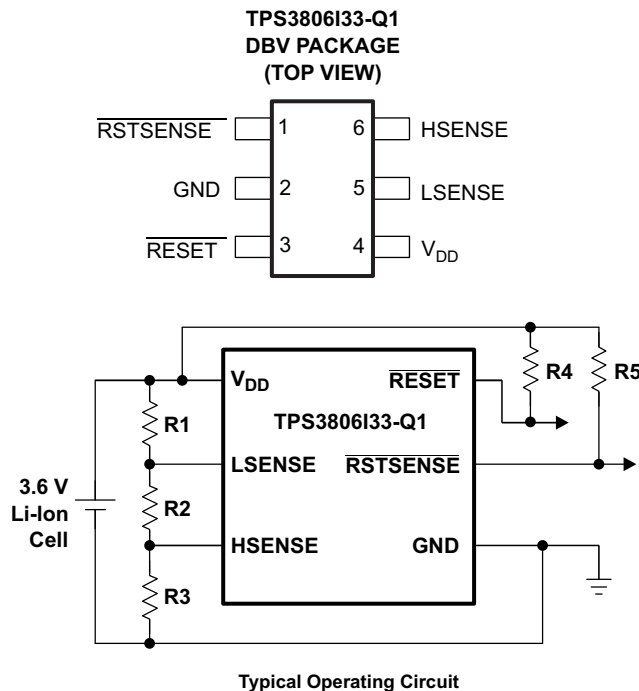
APPLICATIONS

- Voltage Supervisor
- Voltage Detector
- Battery Monitor

DESCRIPTION

The TPS3806I33-Q1 integrates two independent voltage detectors for battery voltage monitoring. During power on, the device asserts $\overline{\text{RESET}}$ and $\overline{\text{RSTSENSE}}$ when supply voltage V_{DD} or the voltage at the LSENSE input becomes higher than 0.8 V. Thereafter, the supervisory circuit monitors V_{DD} and LSENSE, keeping $\overline{\text{RESET}}$ and $\overline{\text{RSTSENSE}}$ active as long as V_{DD} and LSENSE remain below the threshold voltage, V_{IT} . As soon as V_{DD} or LSENSE rises above the threshold voltage V_{IT} , the device deasserts $\overline{\text{RESET}}$ or $\overline{\text{RSTSENSE}}$, respectively. The TPS3806I33-Q1 device has a fixed-sense threshold voltage V_{IT} set by an internal voltage divider at V_{DD} and an adjustable second-LSENSE input. In addition, one can set an upper voltage threshold at HSENSE to allow a wide adjustable hysteresis window.

The devices are available in a 6-pin SOT-23 package. Characterization of the TPS3806I33-Q1 device is for operation over a temperature range of –40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



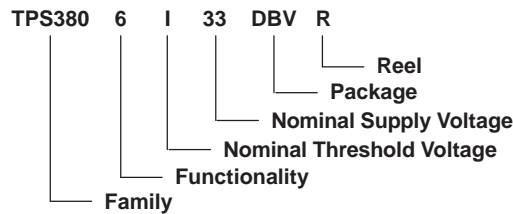
This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

Table 1. ORDERING INFORMATION⁽¹⁾

T _A	PACKAGE	QUANTITY	PART NUMBER	TOP-SIDE SYMBOL	STATUS
-40°C to 125°C	DBV (SOT-23)	Reel of 3000	TPS3806I33QDBVRQ1	PZHQ	Active

(1) For the most-current package and ordering information, see the Package Option Addendum located at the end of this data sheet or refer to the TI Web site at www.ti.com.



ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

	TPS3806I33-Q1	UNIT
Supply voltage, V _{DD} ⁽²⁾	7	V
All other pins ⁽²⁾	-0.3 to 7	V
Maximum low-output current, I _{OL}	5	mA
Maximum high-output current, I _{OH}	-5	mA
Input clamp current, I _{IK} (V _I < 0 or V _I > V _{DD})	±10	mA
Output clamp current, I _{OK} (V _O < 0 or V _O > V _{DD})	±10	mA
Operating free-air temperature range, T _A	-40 to 125	°C
Storage temperature range, T _{stg}	-65 to 150	°C
Electrostatic discharge rating, ESD	Human-body model (HBM) AEC-Q100 Classification Level H2	2 kV
	Charged-device model (CDM) AEC-Q100 Classification Level C4B	750 V

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to GND. For reliable operation, the device must not be continuously operated at 7 V for more than t = 1000 h.

THERMAL INFORMATION

THERMAL METRIC ⁽¹⁾		TPS3806I33-Q1	
		DBV	UNIT
		6 PINS	
θ_{JA}	Junction-to-ambient thermal resistance ⁽²⁾	188.9	°C/W
θ_{JcTop}	Junction-to-case (top) thermal resistance ⁽³⁾	130.9	°C/W
θ_{JB}	Junction-to-board thermal resistance ⁽⁴⁾	34.2	°C/W
ψ_{JT}	Junction-to-top characterization parameter ⁽⁵⁾	25.4	°C/W
ψ_{JB}	Junction-to-board characterization parameter ⁽⁶⁾	33.8	°C/W
θ_{JcBot}	Junction-to-case (bottom) thermal resistance ⁽⁷⁾	N/A	°C/W

- (1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).
- (2) The junction-to-ambient thermal resistance under natural convection is obtained in a simulation on a JEDEC-standard, high-K board, as specified in JESD51-7, in an environment described in JESD51-2a.
- (3) The junction-to-case (top) thermal resistance is obtained by simulating a cold plate test on the package top. No specific JEDEC-standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.
- (4) The junction-to-board thermal resistance is obtained by simulating in an environment with a ring cold plate fixture to control the PCB temperature, as described in JESD51-8.
- (5) The junction-to-top characterization parameter, ψ_{JT} , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA} , using a procedure described in JESD51-2a (sections 6 and 7).
- (6) The junction-to-board characterization parameter, ψ_{JB} , estimates the junction temperature of a device in a real system and is extracted from the simulation data for obtaining θ_{JA} , using a procedure described in JESD51-2a (sections 6 and 7).
- (7) The junction-to-case (bottom) thermal resistance is obtained by simulating a cold plate test on the exposed (power) pad. No specific JEDEC standard test exists, but a close description can be found in the ANSI SEMI standard G30-88.

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, V_{DD}	1.3	6	V
Input voltage, V_I	0	$V_{DD} + 0.3$	V
Operating free-air temperature range, T_A	-40	125	°C

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V _{OL}	Low-level output voltage	V _{DD} = 1.5 V, I _{OL} = 1 mA				V	
		V _{DD} = 3.3 V, I _{OL} = 2 mA			0.3		
		V _{DD} = 6 V, I _{OL} = 3 mA					
Power-up reset voltage ⁽¹⁾		V _{DD} ≥ 0.8 V, I _{OL} = 50 μA			0.2	V	
V _{IT}	Negative-going input threshold voltage ⁽²⁾	LSENSE	T _A = 25°C	1.198	1.207	1.216	V
		TPS3806I33-Q1		2.978	3	3.022	
		LSENSE	T _A = 0°C to 70°C	1.188	1.207	1.226	
		TPS3806I33-Q1		2.952	3	3.048	
		LSENSE	T _A = -40°C to 125°C	1.183	1.207	1.231	
TPS3806I33-Q1	2.94	3		3.06			
V _{hys}	Hysteresis	1.2 V < V _{IT} < 2.5 V		60		mV	
		2.5 V < V _{IT} < 3.5 V		90			
I _I	Input current	LSENSE, HSENSE	-25		25	nA	
I _{OH}	High-level output current	V _{DD} = V _{IT} + 0.2 V, V _{OH} = V _{DD}			300	nA	
I _{DD}	Supply current	V _{DD} = 3.3 V, output unconnected		3	5	μA	
		V _{DD} = 6 V, output unconnected		4	6		
C _i	Input capacitance	V _I = 0 V to V _{DD}		1		pF	

(1) The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. $t_{r,VDD} \geq 15 \mu\text{s/V}$

(2) To ensure best stability of the threshold voltage, place a bypass capacitor (ceramic, 0.1 μF) near the supply terminals.

SWITCHING CHARACTERISTICS

at R_L = 1 MΩ, C_L = 50 pF, T_A = -40°C to 125°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _{PHL}	Propagation (delay) time, high-to-low-level output	V _{DD} to $\overline{\text{RESET}}$ delay	V _{IH} = 1.05 × V _{IT} , V _{IL} = 0.95 × V _{IT}	5	100	μs
		LSENSE to $\overline{\text{RSTSENSE}}$ delay				
t _{PLH}	Propagation (delay) time, low-to-high-level output	V _{DD} to $\overline{\text{RESET}}$ delay				
		HSENSE to $\overline{\text{RSTSENSE}}$ delay				

TIMING REQUIREMENTS

at R_L = 1 MΩ, C_L = 50 pF, T_A = -40°C to 125°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _w	Pulse duration	At V _{DD}	V _{IH} = 1.05 × V _{IT} , V _{IL} = 0.95 × V _{IT}	5.5		μs
		At SENSE				

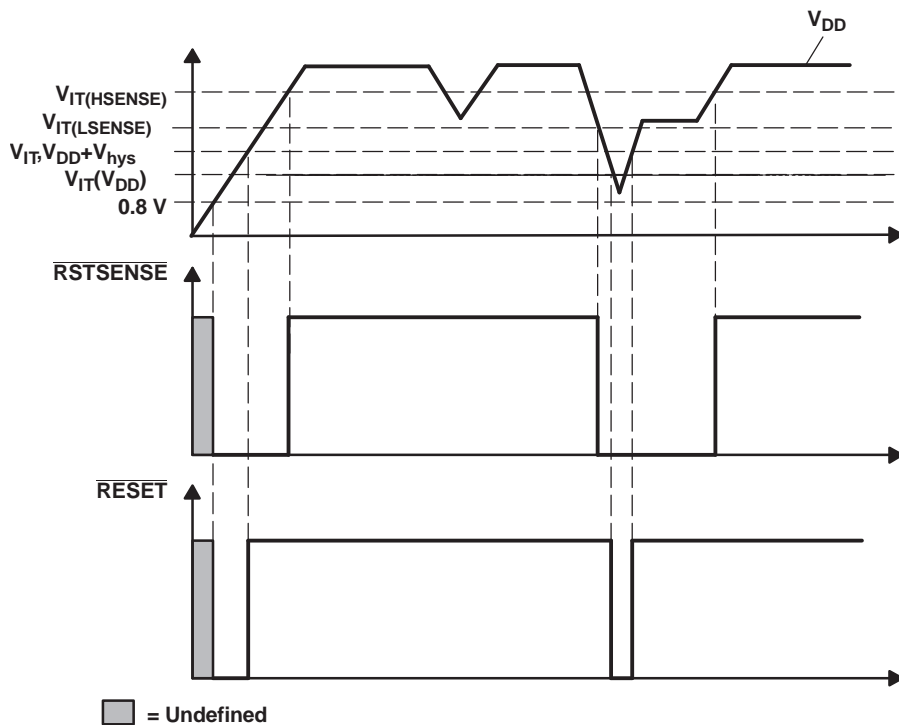
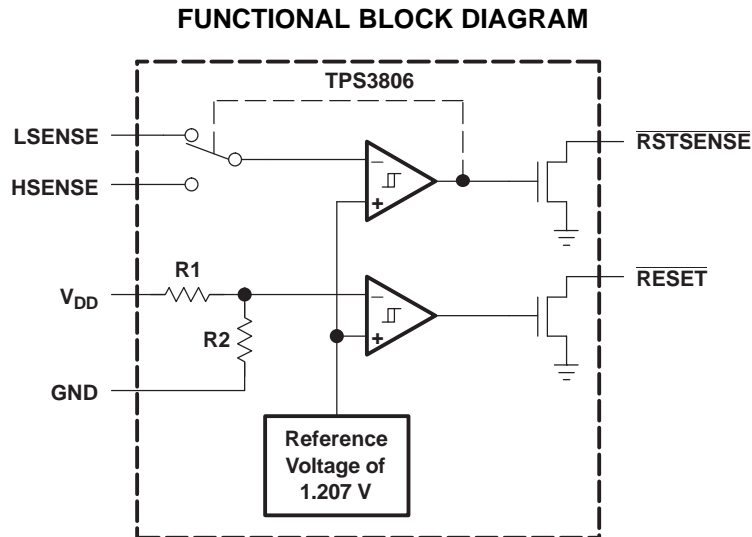


Table 2. TERMINAL FUNCTIONS

TERMINAL		I/O	DESCRIPTION
NAME	NO.		
GND	2	I	Ground
HSENSE	6	I	Adjustable hysteresis input
LSENSE	5	I	Adjustable sense input
\overline{RESET}	3	O	Active-low open-drain reset output (from V_{DD})
$\overline{RSTSENSE}$	1	O	Active-low open-drain reset output (from LSENSE)
V_{DD}	4	I	Input supply voltage and fixed sense input

FUNCTION AND TRUTH TABLE

TPS3806I33-Q1			
$V_{DD} > V_{IT}$	\overline{RESET}	$LSENSE > V_{IT}$	$\overline{RSTSENSE}$
0	L	0	L
1	H	1	H



Detailed Description

Operation

The TPS3806I33-Q1 monitors battery voltage and asserts $\overline{\text{RESET}}$ when a battery becomes discharged below a certain threshold voltage. A comparator monitors the battery voltage via an external resistor divider. When the voltage at the LSENSE input drops below the internal reference voltage, the $\overline{\text{RSTSENSE}}$ output pulls low. The output remains low until the battery is replaced, or recharged above a second higher trip-point, set at HSENSE. One can monitor a second voltage at V_{DD} . The independent $\overline{\text{RESET}}$ output pulls low when the voltage at V_{DD} drops below the fixed threshold voltage. Because the TPS3806I33-Q1 outputs are open-drain MOSFETs, most applications may require a pullup resistor.

Programming the Threshold Voltage Levels

Calculate the low-voltage threshold at LSENSE according to [Equation 1](#):

$$V_{(\text{LSENSE})} = V_{\text{ref}} \left(\frac{R1 + R2 + R3}{R2 + R3} \right) \quad (1)$$

where $V_{\text{ref}} = 1.207 \text{ V}$

Calculate the high-voltage threshold at HSENSE as shown in [Equation 2](#):

$$V_{(\text{HSENSE})} = V_{\text{ref}} \left(\frac{R1 + R2 + R3}{R3} \right) \quad (2)$$

where $V_{\text{ref}} = 1.207 \text{ V}$

To minimize battery current draw, TI recommends using $1 \text{ M}\Omega$ as the total resistor value $R_{(\text{tot})}$, with $R_{(\text{tot})} = R1 + R2 + R3$.

TYPICAL CHARACTERISTICS

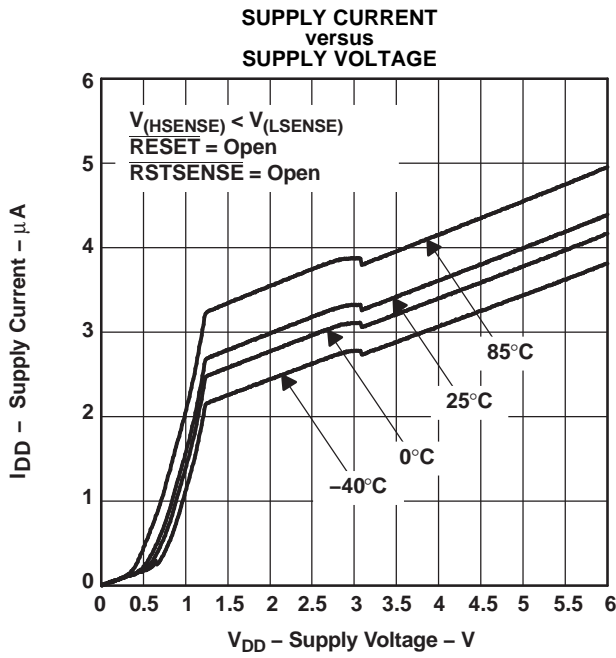


Figure 1.

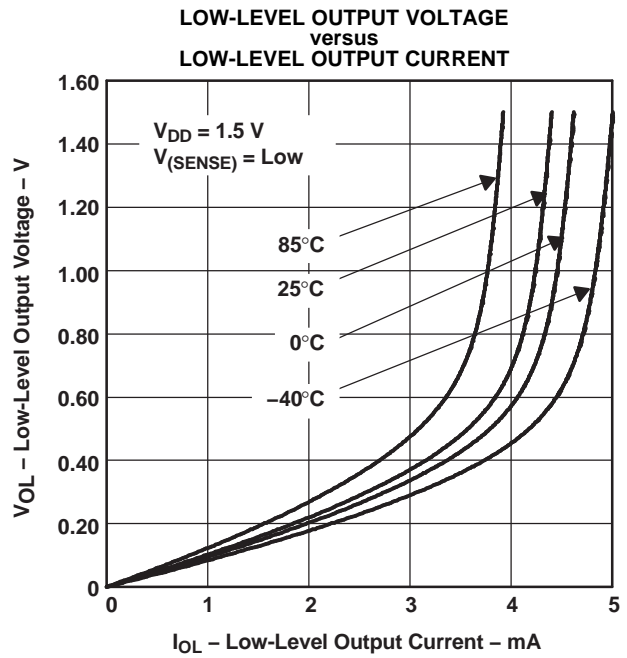


Figure 2.

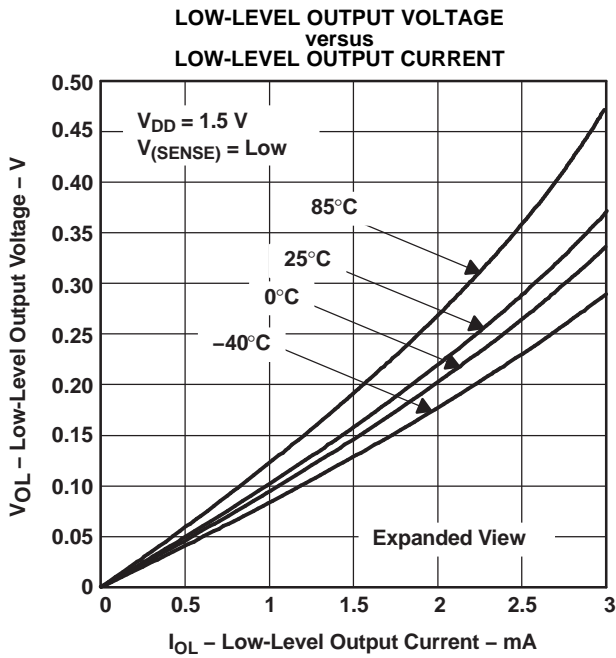


Figure 3.

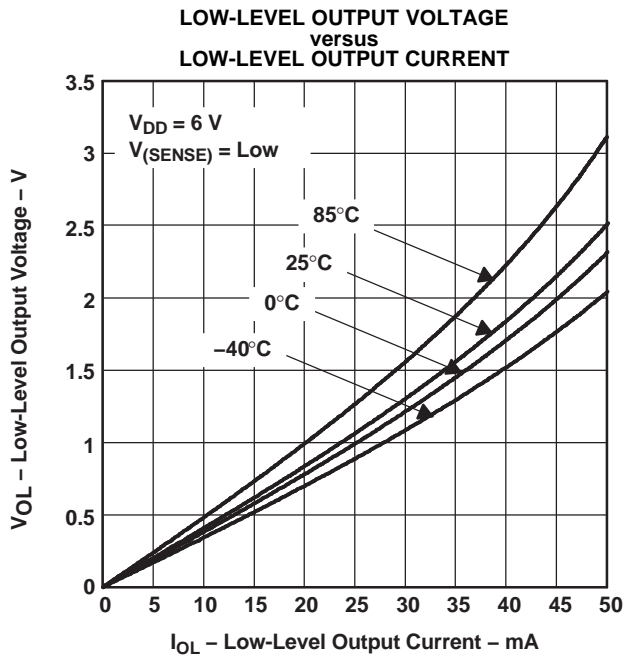


Figure 4.

TYPICAL CHARACTERISTICS (continued)

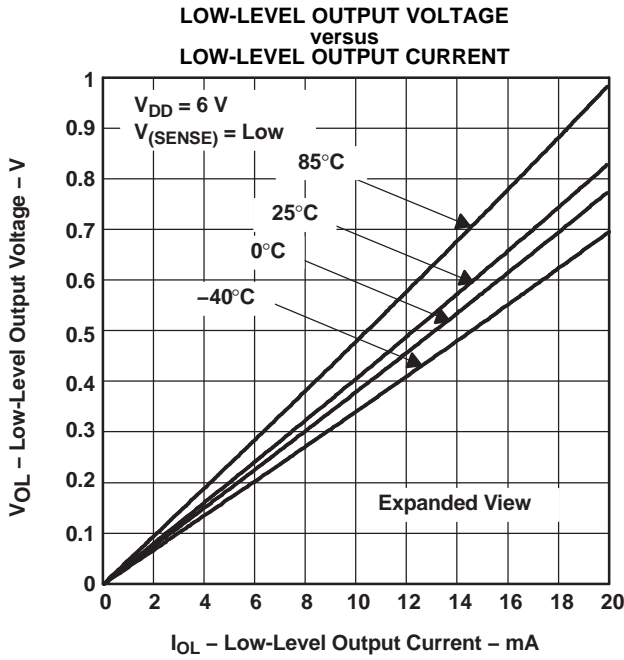


Figure 5.

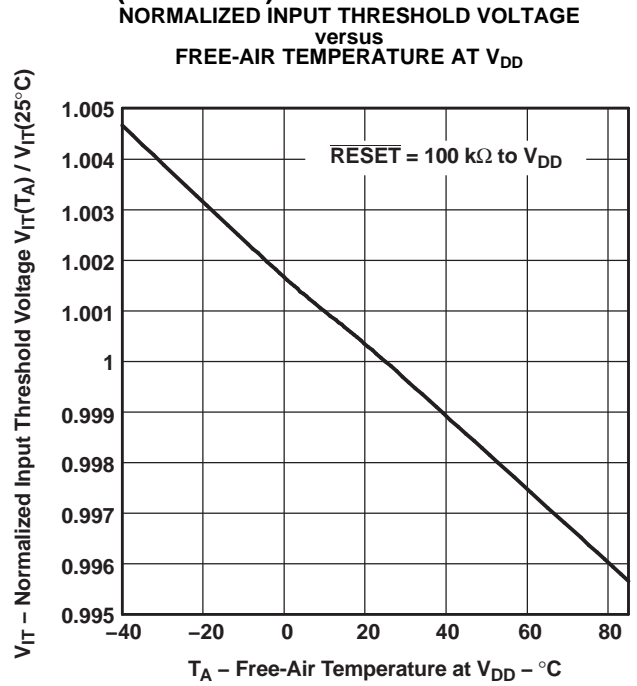


Figure 6.

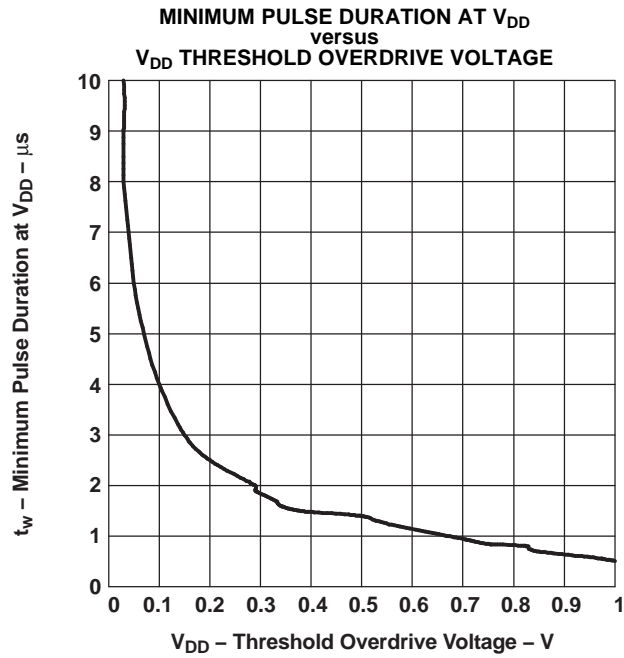


Figure 7.

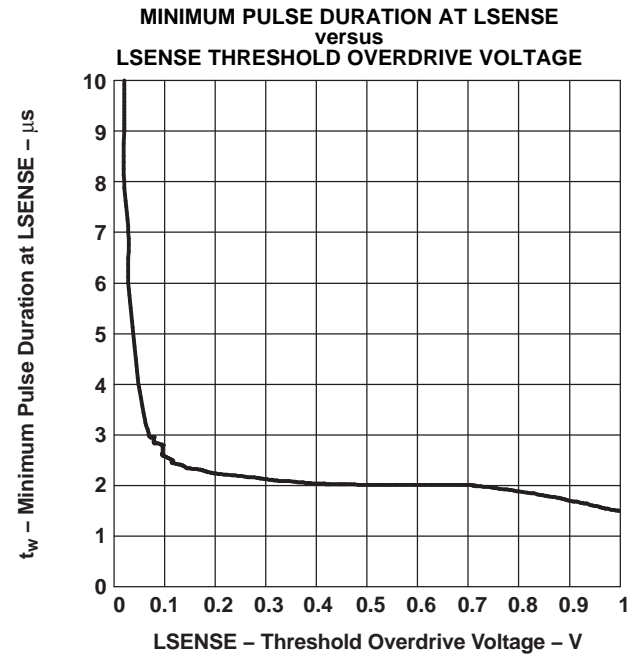


Figure 8.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TPS3806I33QDBVRQ1	ACTIVE	SOT-23	DBV	6	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	PZHQ	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

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OTHER QUALIFIED VERSIONS OF TPS3806I33-Q1 :

- Catalog: [TPS3806I33](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3806I33QDBVRQ1	SOT-23	DBV	6	3000	178.0	9.0	3.23	3.17	1.37	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3806I33QDBVRQ1	SOT-23	DBV	6	3000	180.0	180.0	18.0

MECHANICAL DATA

DBV (R-PDSO-G6)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Leads 1,2,3 may be wider than leads 4,5,6 for package orientation.
- Falls within JEDEC MO-178 Variation AB, except minimum lead width.

DBV (R-PDSO-G6)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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